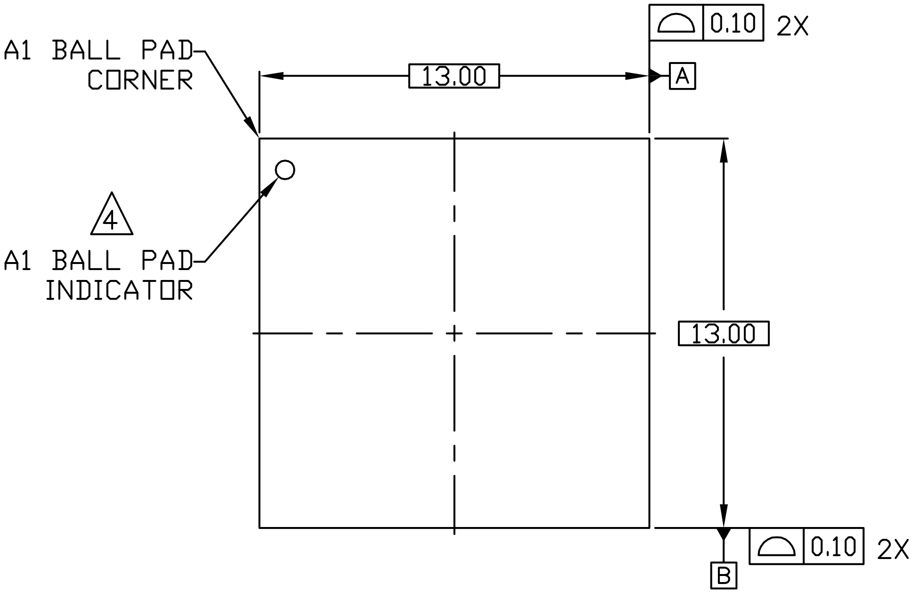
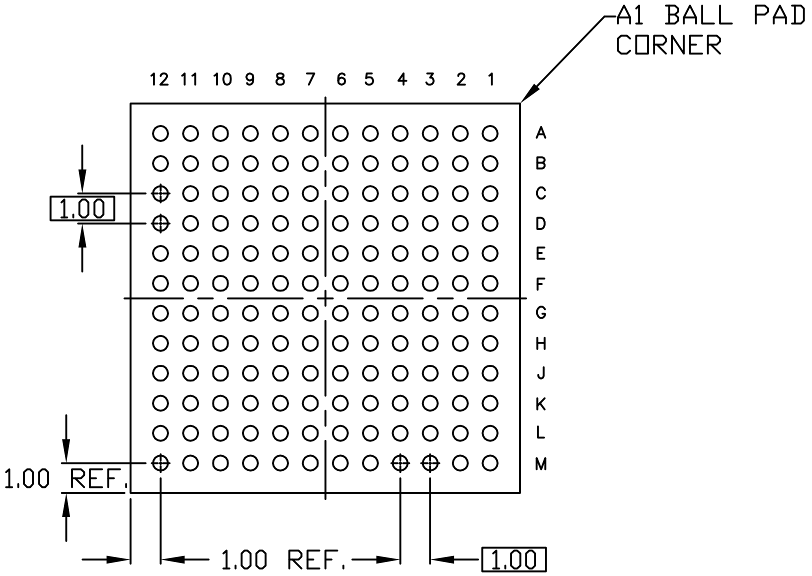
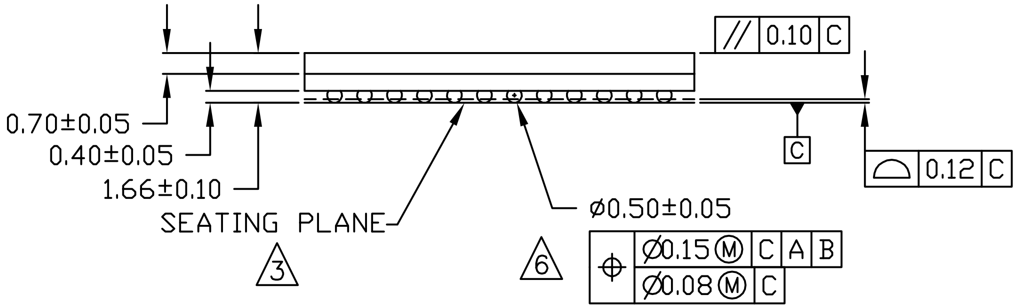


TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.
3. PRIMARY DATUM -C- AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. A1 BALL PAD CORNER I.D.
5. BASIC SOLDER BALL PITCH IS 100 MM.
6. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
7. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbFREE (+) PKG. CODES.
8. PACKAGE CODE: X144-2, X144T-1

-DRAWING NOT TO SCALE-

TITLE:
PACKAGE OUTLINE, 144 BALLS, TECSBGA/CSBGA
13x13mm BODY, 4 LAYER 1.00MM PITCH

APPROVAL	DOCUMENT CONTROL NO.	REV.	
EDEN CHEN 5/6/10	21-0314	B	1/1